

Amendments to Claims

This listing of claims will replace all prior versions and listing of claims in the application:

Listing of Claims

1-4. (canceled)

5. (Previously presented) An integrated package comprising:

a first wafer having a first surface;

a second wafer having a first surface bonded at a first perimeter to the first surface of the first wafer;

a recess formed in the first surface of the first wafer between the first perimeter and a second perimeter situated within the first perimeter for a window situated within the second perimeter; and

a seal between the first and second wafers at the first perimeter, wherein the seal includes a spacer material and a layer of malleable material.

6. (Previously presented) The package of claim 5, wherein the seal further comprises a layer of bondable material.

7. (Previously presented) The package of claim 6, further comprising structural supports in the recess of the

first wafer.

8. (Previously presented) The package of claim 7, further comprising at least one pumpout opening in the first wafer.

9. (Previously presented) The package of claim 8, wherein the first and second wafers comprise silicon.

10-51. (Canceled)